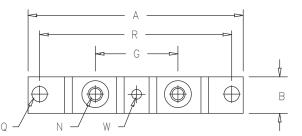
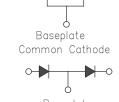
Ultra Fast Recovery Module UFT40010 — UFT40020









copper

Baseplate D=Doubler Notes: Baseplate: Nickel plated

Dim. Inches		Millimeters		
Min.	Max.	Min.	Max.	Notes
E 0.120	3.630 0.800 0.630 0.130 0.510 BSC		92.20 20.32 16.00 3.30 12.95 2 BSC	1/4-20
Q 0.275 R 3.15 U 0.600 V 0.312 W 0.180	0 BSC	6.99 80.0 ⁻ 15.24 7.92 4.57	7.37 1 BSC 8.64 4.95	Dia.

Microsemi	Working Peak	Repetitive Peak
Catalog Number	Reverse Voltage	Reverse Voltage
UFT40010*	100V	100V
UFT40015*	150V	150V
UFT40020*	200V	200V
*Add Suffix	A for Common And	ode, D for Doubler

- Ultra Fast Recovery
- 175°C Junction Temperature
- 2 X 200 Amp current rating
- ROHS Compliant

Electrical Characteristics

Average forward current per pkg
Average forward current per leg
Maximum surge current per leg
Max peak forward voltage per leg
Max peak reverse recovery time per leg
Max peak reverse current per leg
Max peak reverse current per leg
Typical junction capacitance per leg

F(AV) 200 Amps FSM 2600 Amps VFM 0.975 Volts trr 100 nS RM 8 mA RM 50 uA CJ 1400 pF

|F(AV) 400 Amps

 ^{T}C = 135°C, Square wave, $^{R}\theta JC$ = 0.12°C/W ^{T}C = 135°C, Square wave, $^{R}\theta JC$ = 0.24°C/W 8.3ms, half sine, ^{T}J = 175°C

|FM = 200A:TJ = 25°C*

 $IF = 1A, VR = 30V \text{ di/dt} = 50A/\mu S$

VRRM, TJ = 125°C* VRRM, TJ = 25°C VR = 10V, TJ = 25°C

*Pulse test: Pulse width 300 µsec, Duty cycle 2%

Thermal and Mechanical Characteristics TSTG -55℃ to 175℃ Storage temp range ΤJ Operating junction temp range -55°C to 175°C 0.24°C/W Junction to case 0.12°C/W Junction to case 0.08°C/W Case to sink R OJC Max thermal resistance per leg R OJC Max thermal resistance per pkg Recs Typical thermal resistance (greased) Terminal Torque 35-50 inch pounds Mounting Base Torque (outside holes) 30-40 inch pounds

Mounting Base Torque (center hole)
center hole must be torqued first

Weight

So 40 Inch pounds
8—10 inch pounds
2.8 ounces (75 grams) typical



UFT40010 - UFT40020

Figure 1 Typical Forward Characteristics — Per Leg 1000 800 600 400 200 100 80 60 40 Amperes 2500 20 Instantaneous Forward Current — 10 8.0 6.0 4.0 2.0 1.0 .2 .4 .6 .8 1.0 1.2 1.4 1.6 Instantaneous Forward Voltage - Volts

Figure 3
Typical Junction Capacitance - Per Leg

10000

1000

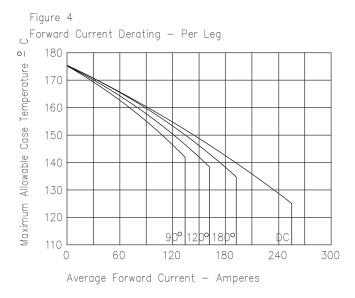
1000

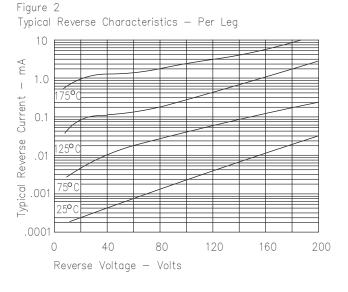
0.1

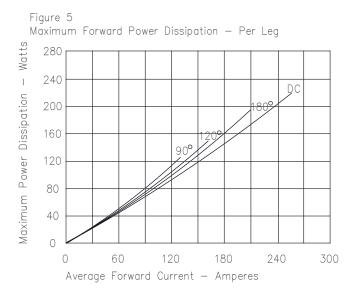
1.0

100

Reverse Voltage - Volts







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